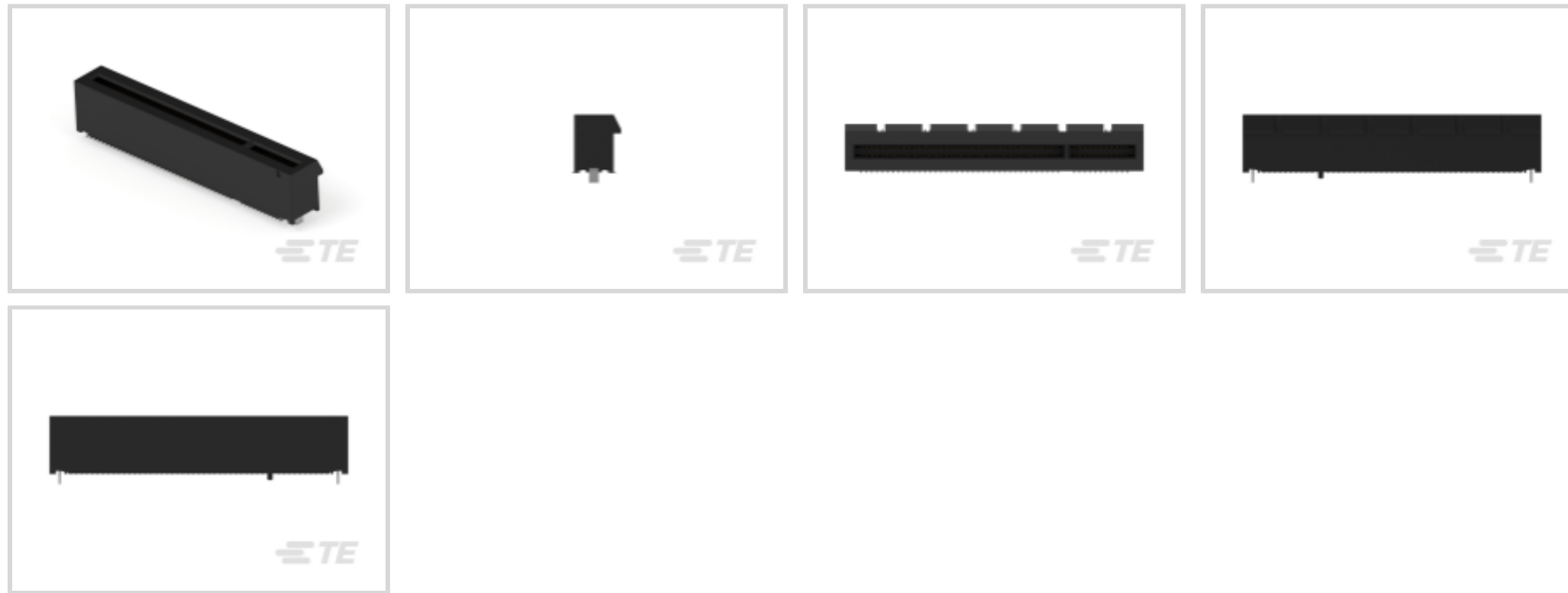




TE Internal #: 2384030-3  
 PCI & PCI Express Connectors, Board-to-Board, 98 Position, .04 in [1 mm] Centerline, Vertical, Black, Height 11.25 mm [.44 in], Width 8.2 mm [.32 in]

[View on TE.com >](#)

Connectors > PCB Connectors > Card Edge Connectors > PCI & PCI Express Connectors



Connector System: **Board-to-Board**  
 Number of Positions: **98**  
 PCI Generation: **5**  
 Centerline (Pitch): **1 mm [.04 in]**  
 Termination Post & Tail Length: **1.1 mm [.043 in]**

**Features**

**Product Type Features**

Connector System	Board-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

**Configuration Features**

Number of Positions	98
PCB Mount Orientation	Vertical
Ejector	Without

**Contact Features**

Termination Post & Tail Length	1.1 mm [.043 in]
Contact Thickness	3 – 8 μin
Contact Current Rating (Max)	1.1 A

**Termination Features**

Termination Method to Printed Circuit Board	Surface Mount
Termination Post & Tail Length	1.1 mm [.043 in]

**Mechanical Attachment**



PCB Mount Retention Type	Tab
Connector Mounting Type	Board Mount

### Housing Features

Centerline (Pitch)	1 mm [.04 in]
Housing Color	Black

### Dimensions

Connector Height	11.25 mm [.44 in]
Connector Width	8.2 mm [.32 in]

### Usage Conditions

Operating Temperature Range	-40 – 85 °C [-40 – 185 °F]
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### Operation/Application

Circuit Application	High Speed Data
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### Industry Standards

PCI Generation	5
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## Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not reviewed for solder process capability

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits

as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

## Compatible Parts



## Documents

### Product Drawings

[PCIE5,SMT,1.9TAB+C-POS,98P,GF,WO ML,HT](#)

English

### CAD Files

Customer View Model

[ENG\\_CVM\\_CVM\\_2384030-3\\_A.3d\\_igs.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_2384030-3\\_A.3d\\_stp.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_2384030-3\\_A.2d\\_dxf.zip](#)

English

[3D PDF](#)

3D

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

### Product Specifications

[Application Specification](#)

English